

[0046] Figs. 11(A)-11(B) are explanatory schematics of resin sealing of the lead frame according to the third exemplary embodiment;

[0047] Fig. 12 is an explanatory schematic of a method to cut the pressing tab according to the exemplary embodiment;

[0048] Figs. 13(A)-13(C) are explanatory schematics of a piezoelectric oscillator according to the third exemplary embodiment;

[0049] Figs. 14(A)-14(B) are schematics illustrating the mounting state of the piezoelectric oscillator according to the third exemplary embodiment;

[0050] Figs. 15(A)-15(B) are explanatory schematics of a lead frame according to a fourth exemplary embodiment;

[0051] Fig. 16 is an explanatory schematic of resin sealing of the lead frame according to the fourth exemplary embodiment;

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[0052] Figs. 17(A)-17^C(~~B~~) are explanatory schematics of a piezoelectric oscillator according to the fourth exemplary embodiment;

[0053] Figs. 18(A)-18(B) are explanatory schematics of the mounting method of the piezoelectric oscillator according to the fourth exemplary embodiment;

[0054] Figs. 19(A)-19(C) are disassembled perspective views of a piezoelectric oscillator according to a fifth exemplary embodiment;

[0055] Figs. 20(A)-20(C) are disassembled perspective views of a piezoelectric oscillator according to a sixth exemplary embodiment;

[0056] Figs. 21(A)-21(C) are disassembled perspective views of a piezoelectric oscillator according to a seventh exemplary embodiment;

[0057] Fig. 22 is an explanatory schematic of a connecting lead according to another exemplary embodiment;

[0058] Figs. 23(A)-23(C) explanatory diagrams of a mounting lead according to another exemplary embodiment;

[0059] Figs. 24(A)-24(B) are schematics illustrating a modification of a mounting lead;

[0060] Figs. 25(A)-25(G) are schematics illustrating mounting terminals formed in irregular shapes;

[0061] Fig. 26 is a schematic illustrating the state of mounting terminals formed in irregular shapes exposed at the lower face of the resin package;